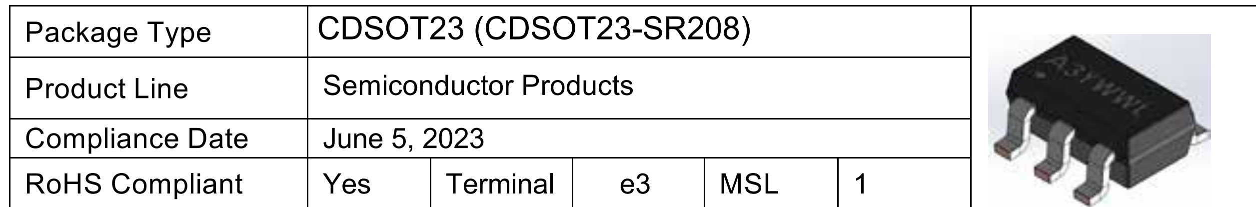
MATERIAL DECLARATION SHEET



Package Type	CDSOT23 (CDSOT23-SR208)				
Product Line	Semiconductor Products				
Compliance Date	June 5, 2023				
RoHS Compliant	Yes	Terminal	e3	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.008465	Amorphous Silica	60676-86-0	91.69	46.527	50.744
				Epoxy Resin A	Proprietary	4.17	2.114	
				Epoxy Resin B	29690-82-2	1.41	0.718	
				Phenol Resin	Proprietary	2.15	1.089	
				Carbon Black	1333-86-4	0.58	0.296	
2	Leadframe	Copper Alloy	0.006929	Copper	7440-50-8	97.399	40.448	41.529
				Iron	7439-89-6	2.389	0.992	
				Phosphorus	7723-14-0	0.076	0.032	
				Zinc	7440-66-6	0.127	0.053	
				Lead	7439-92-1	0.009	0.004	
		Silver Plating	0.000007	Silver	7440-22-4	100.00	0.040	0.040
3	Chip	Silicon	0.000463	Silicon	7440-21-3	91.884	2.539	2.775
				Nickel	7440-02-0	6.125	0.169	
				Aluminum	7429-90-5	1.612	0.057	
				Gold	7440-57-5	0.379	0.010	
4	Die Attach	Silver Epoxy	0.000126	Silver	7440-22-4	95.190	0.7168	0.753
				Bisphenol-F-(Epichlorhydrin); Epoxy resin	9003-36-5	2.756	0.0207	
				1,4-Bis(2,3-epoxypropoxy) butane	2425-79-8	1.061	0.0080	
				Aromatic polyamine	Proprietary	0.965	0.0073	
				Adipic Acid	124-04-9	0.028	0.0002	
5	Bond Wires	Copper	0.000051	Copper	7440-50-8	98.260	0.300	0.305
				Non - Cu element	Proprietary	1.740	0.005	
6	Lead Finish	Matte Tin	0.000643	Tin	7440-31-5	100.00	3.854	3.854
		Total Weight	0.016684					

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.

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